

TWO-PART THERMALLY CONDUCTIVE LIQUID GAP FILLER, 4.0 W/m-K

Features and Benefits

- Superior thermal performance
- 4.0 W/m-K thermal conductivity
- Easy to dispense
- Easy storage
- Ultra-conforming for fragile and low stress applications
- Ambient or accelerated cure schedules in elevated temperature



Typical Applications

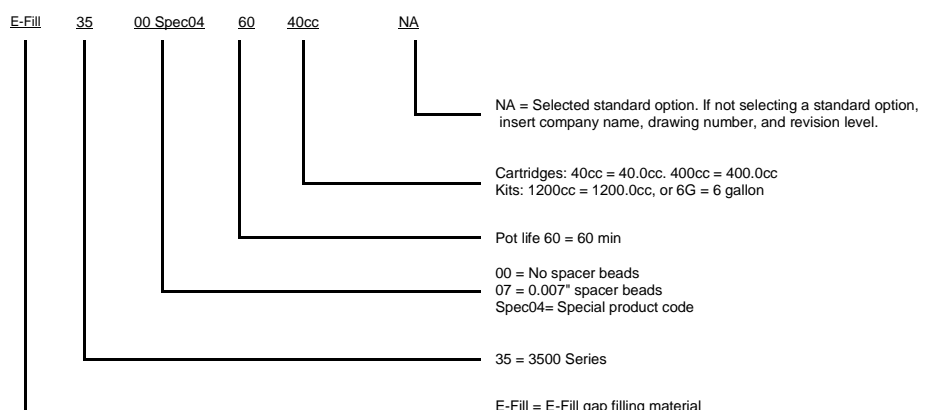
- Automotive electronics
- PCBA to housing
- Discrete components to housing
- Fiber optic telecommunications equipment

E-Fill 3500 Spec04 offers excellent thermal performance and superior conformability. It is a two-component liquid gap filling material, cured at either room or elevated temperature to speed up the curing process. The pre-curing material possesses good thixotropic characteristics as well as low viscosity which is an ideal solution for dispensing. After cured, the mixture became a low modulus elastomer to relieve stresses during thermal cycling.

E-Fill 3500 Spec04 will lightly adhere to surfaces, thus improving surface area contact.

PROPERTIES	E-Fill 3500 Spec04	Test Method
Construction & Composition	Soft silicone elastomer	—
Color	Part A: White / Part B: Blue	Visual
Viscosity (Spindle#7 @ 12 RPM)	Part A: 395000cP / Part B: 415000cP	ASTM D2196
Density	3.15 g/cm ³	—
Mix Ratio	1:1	—
Shelf Life @ 25 °C	6 months	—
PROPERTIES AS CURED		
Color	Blue	Visual
Hardness	65 Shore 00	ASTM D2240
Continuous Use Temp	-60 to 200 °C	—
Thermal Conductivity	4.0 W/m-K	ASTM D5470 (modified)
Dielectric Strength	200 V/mil	ASTM D149
Dielectric Constant @ 1MHz	12.4	ASTM D150
Volume Resistivity	10 ¹³ ohm.cm	ASTM D257
Flame Rating	U.L.94 V-O	U.L. 94
CURE SCHEDULE		
Pot Life @ 25 °C	30 min	—
Cure @ 25 °C	3 hours	—
Cure @ 100 °C	10 min	—
Please contact us for other special requirements		

Product Code and Descriptions



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产品特点

- 出众的导热性能
- 导热率 4.0 W/m-K
- 适合点胶
- 易于储存
- 超好贴服性，针对易碎和低压应用设计
- 可室温固化或加速固化



一般应用

- 汽车电子
- 独立元器件到外壳
- 印制电路板装配到外壳
- 光纤通讯设备

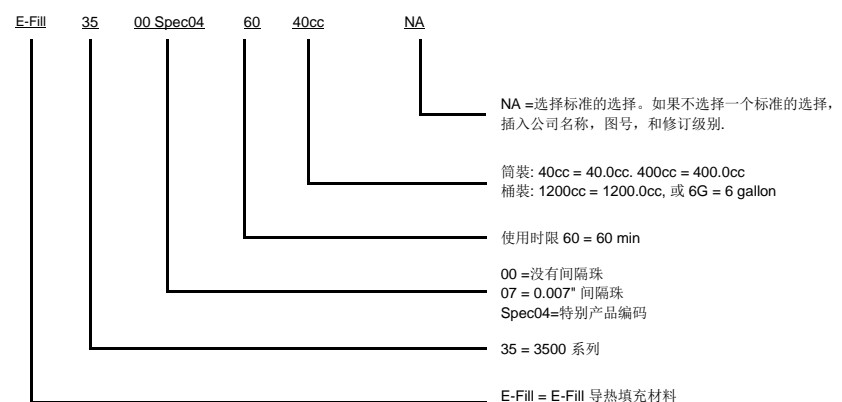
E-Fill 3500 Spec04 具有优异的热性能和卓越的舒适性。它是一种双组分液体的空隙填充材料，可经由常温自然固化或高温加速固化成型。固化前材料具有良好的触变性以及低粘度，使 E-Fill 3500 Spec04 适合用于点胶上。固化后，混合成型后为一个低模量弹性体，在热循环组件中缓冲压力。

E-Fill 3500 Spec04 带有轻微黏性从而提高接触面积，加强其导热效果。

固化前特性	E-Fill 3500 Spec04	测试方法
成份	聚硅酮弹性体	-
外观	A 组分: 白色 / B 组分: 蓝色	Visual
稠度(7号转子 @ 12 RPM 转速)	A 组分: 395000cP / B 组分: 415000cP	ASTM D2196
密度	3.15 g/cm ³	ASTM D792
混合比	1:1	-
保质期 @ 25 °C	6个月	-
固化后特性		
颜色	蓝色	Visual
硬度	65 Shore 00	ASTM D2240
连续使用温度	-60 to 200 °C	-
导热率	4.0 W/m-K	ASTM D5470 (modified)
介电强度	200 V/mil	ASTM D149
介电常数@ 1MHz	12.4	ASTM D150
体积电阻率	10 ¹³ ohm.cm	ASTM D257
UL 防火评级	U.L.94 V-O	U.L. 94
固化设定		
使用时限@ 25 °C (min)	30 min	-
固化@ 25 °C (hrs)	3 hours	-
固化@ 100 °C (min)	10 min	-

如有其他特殊要求，请联系我们

产品编码及描述



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